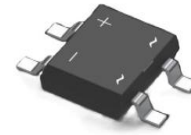


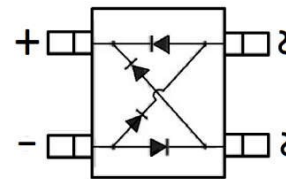
0.8A Glass Passivated Bridge Rectifier

Features

- Glass Passivated Chip Junction
- Low Reverse Voltage Leakage Current
- High Surge Current Capability
- Low Forward Voltage Drop
- Reverse Voltage : 50 to 1000V
- Forward Current : 0.8A
- High temperature soldering : 260 °C/10s at terminals



MB-F



Applications

- Switching power supply

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbol	MB 05F	MB 1F	MB 2F	MB 4F	MB 6F	MB 8F	MB 10F	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_A=40^{\circ}C$	$I_{F(AV)}$	0.8							A
Peak Forward Surge Current 8.3mS single half sine wave superimposed on rated load (JEDEC method)	I_{FSM}	30							A
Maximum Instantaneous Forward Voltage @0.8A	V_F	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^{\circ}C$	5.0							μA
	$T_A=125^{\circ}C$	500							
Typical Junction Capacitance (Note 1)	C_J	13							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	60							$^{\circ}C/W$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	(-55 to +150)							$^{\circ}C$

Notes:

1. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts.
2. Thermal Resistance test performed in accordance with JESD-51. Unit mounted on 15mm*12mm*1.6mm AL pad attach 195mm*110mm*10mm steel plate.

Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Average Rectified Output Current Derating Curve

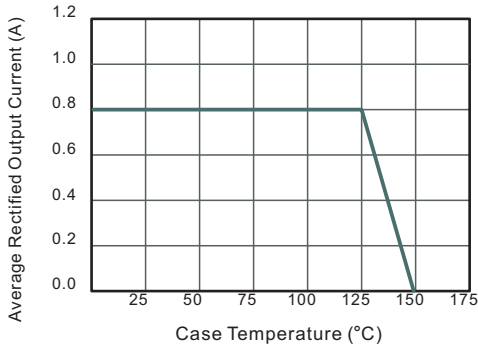


Fig.2 Typical Reverse Characteristics

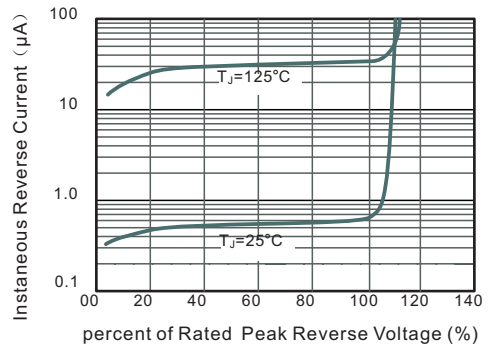


Fig.3 Typical Instantaneous Forward Characteristics

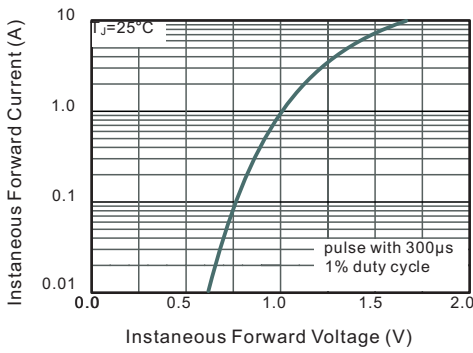


Fig.4 Typical Junction Capacitance

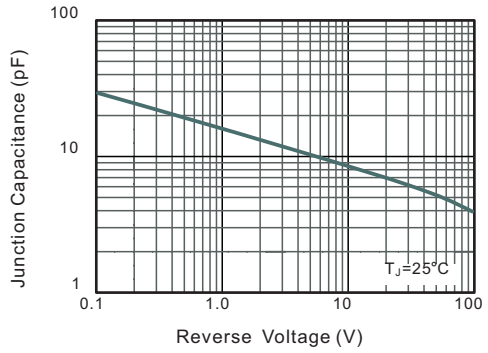
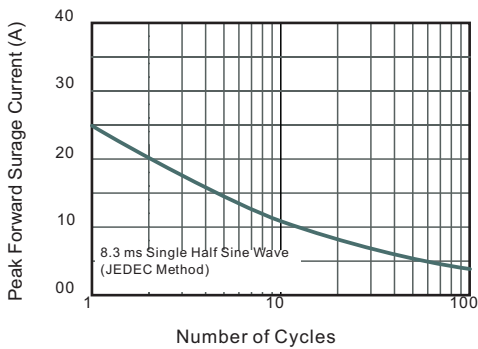
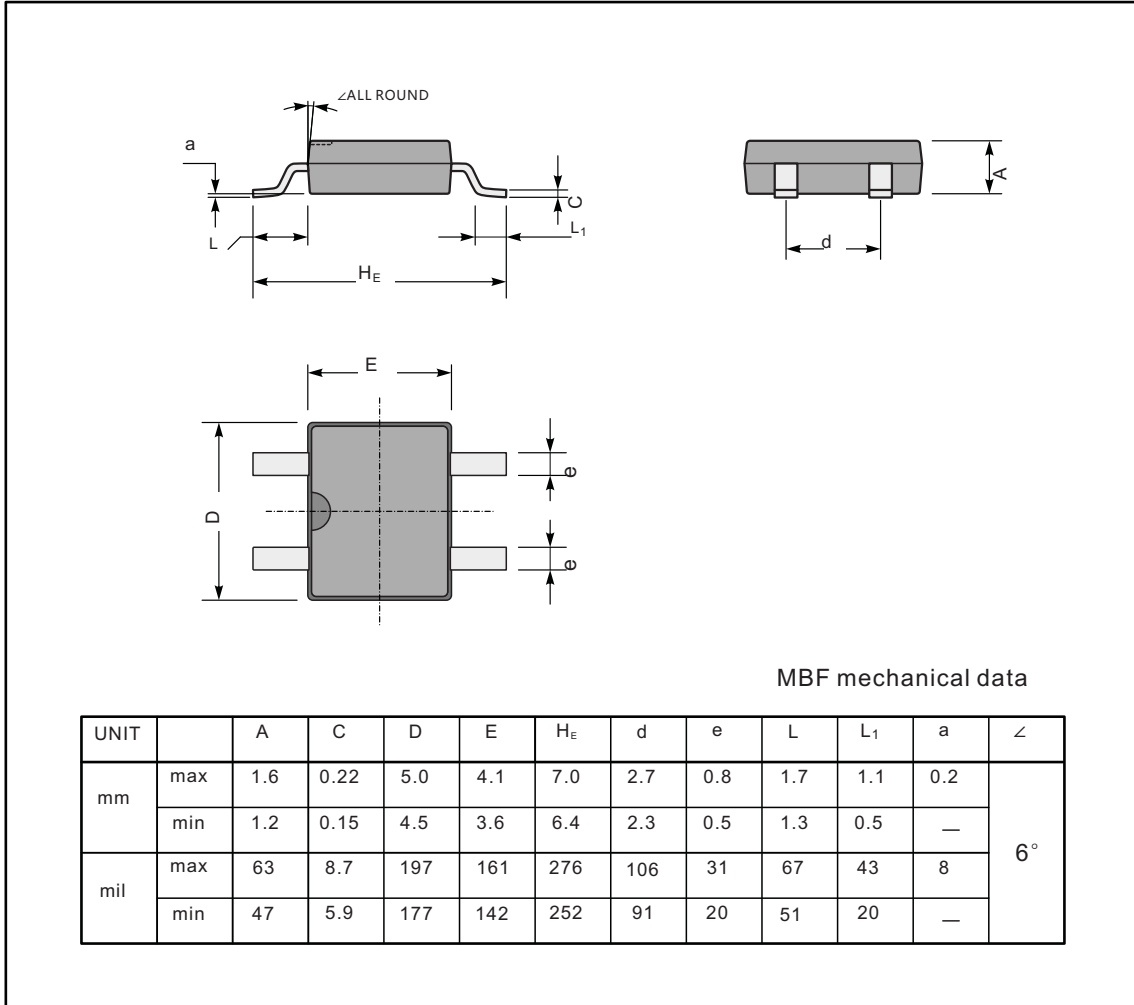


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

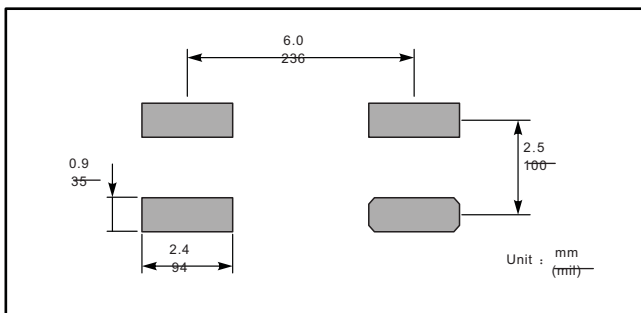


Package Outlines (Dimensions in mm)

Plastic surface mounted package(MB-F)

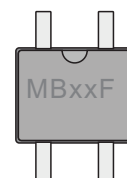


The recommended mounting pad size



Marking

Type number	Marking code
MB1F	MB1F
MB2F	MB2F
MB4F	MB4F
MB6F	MB6F
MB8F	MB8F
MB10F	MB10F



***Important Usage Information and Disclaimer**

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